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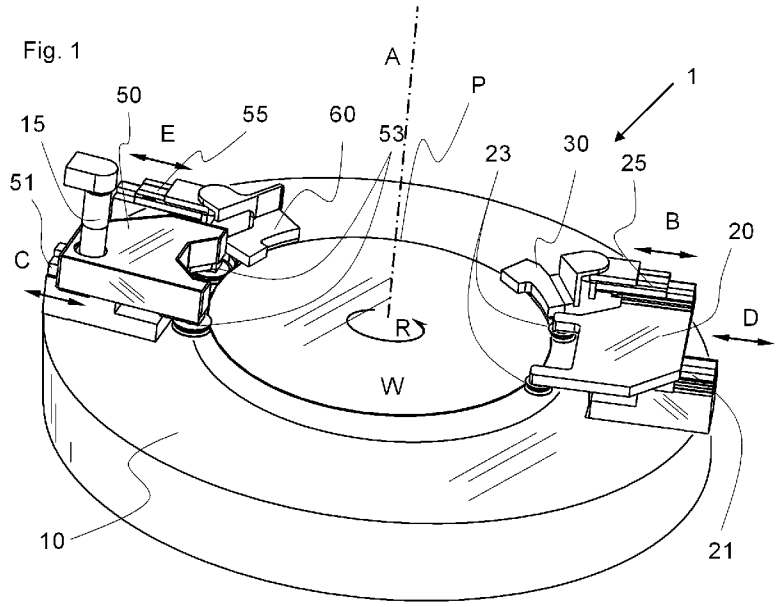
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(54) Title: DEVICE AND PROCESS FOR WET TREATING A PERIPHERAL AREA OF A WAFER-SHAPED ARTICLE

Fig. 1



(57) Abstract: Disclosed is a device (1) for wet treating a peripheral area of a wafer-shaped article W. The device comprises holding means (20, 50) for holding and rotating the wafer-shaped article at its edge, a first liquid treatment unit (30) for supplying liquid towards the peripheral area, and a second liquid treatment unit (60) for supplying liquid towards the peripheral area. The holding means comprise rollers (23, 53) for driving the wafer-shaped article at its edge. The first liquid treatment unit comprises a first liquid carrier for providing a first liquid to wet a first section of the peripheral area, a first liquid supply nozzle for supplying liquid to the first liquid carrier, and a first liquid discharging channel for removing liquid from the first liquid carrier. The second liquid treatment unit comprises, a second liquid carrier for providing a second liquid to wet a second section of the peripheral area, a second liquid supply nozzle for supplying liquid to the second liquid carrier, a second liquid discharging channel for removing liquid from the second liquid carrier, and a second gas treatment section with a gas supply nozzle for supplying gas towards the peripheral area, which has been treated with the second liquid for removing most of the second liquid from the peripheral area, and with a gas discharge channel for discharging gas and removed liquid. Furthermore an associated method is disclosed.

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